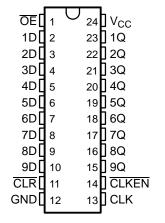
www.ti.com

SCAS305I-MARCH 1993-REVISED FEBRUARY 2005

#### **FEATURES**

- Operates From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 7.9 ns at 3.3 V
- Typical V<sub>OLP</sub> (Output Ground Bounce)
   <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
   >2 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V<sub>CC</sub>)
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

# DB, DGV, DW, NS, OR PW PACKAGE (TOP VIEW)



### **DESCRIPTION/ORDERING INFORMATION**

This 9-bit bus-interface flip-flop is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

The SN74LVC823A is designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

With the clock-enable (CLKEN) input low, the nine D-type edge-triggered flip-flops enter data on the low-to-high transitions of the clock. Taking CLKEN high disables the clock buffer, latching the outputs. This device has noninverting data (D) inputs. Taking the clear (CLR) input low causes the nine Q outputs to go low, independently of the clock.

#### ORDERING INFORMATION

T <sub>A</sub>	PACK	AGE <sup>(1)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	SOIC - DW	Tube of 25	SN74LVC823ADW	LVC823A	
	SOIC - DW	Reel of 2000	SN74LVC823ADWR	LVC023A	
-40°C to 85°C	SOP - NS	Reel of 2000	SN74LVC823ANSR	LVC823A	
	SSOP – DB	Reel of 2000	SN74LVC823ADBR	LC823A	
-40 C to 65 C		Tube of 60	SN74LVC823APW		
	TSSOP - PW	Reel of 2000	SN74LVC823APWR	LC823A	
		Reel of 250	SN74LVC823APWT		
	TVSOP - DGV	Reel of 2000	SN74LVC823ADGVR	LC823A	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SCAS305I-MARCH 1993-REVISED FEBRUARY 2005



## **DESCRIPTION/ORDERING INFORMATION (CONTINUED)**

A buffered output-enable  $(\overline{OE})$  input can be used to place the nine outputs in either a normal logic state (high or low logic levels) or the high-impedance state.  $\overline{OE}$  does not affect the internal operations of the latch. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

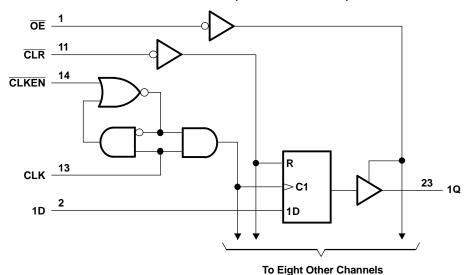
This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

# FUNCTION TABLE (EACH FLIP-FLOP)

		INPUTS			OUTPUT
ŌĒ	CLR	CLKEN	CLK	D	Q
L	L	Χ	Χ	Х	L
L	Н	L	$\uparrow$	Н	Н
L	Н	L	$\uparrow$	L	L
L	Н	Н	Χ	X	$Q_0$
Н	X	Χ	Χ	X	Z

### **LOGIC DIAGRAM (POSITIVE LOGIC)**







# Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage range		-0.5	6.5	V
VI	Input voltage range <sup>(2)</sup>		-0.5	6.5	V
Vo	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>		-0.5	6.5	V
Vo	Voltage range applied to any output in the h	nigh or low state (2)(3)	-0.5	$V_{CC} + 0.5$	V
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
I <sub>O</sub>	Continuous output current			±50	mA
	Continuous current through V <sub>CC</sub> or GND			±100	mA
		DB package		63	
		DGV package		86	
$\theta_{JA}$	Package thermal impedance (4)	DW package		46	°C/W
		NS package		65	
		PW package		88	
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

# Recommended Operating Conditions<sup>(1)</sup>

			MIN	MAX	UNIT
V	Cupply valtage	Operating	1.65	3.6	V
$V_{CC}$	Supply voltage	Data retention only	1.5		V
		V <sub>CC</sub> = 1.65 V to 1.95 V	$0.65 \times V_{CC}$		
$V_{IH}$	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		
		V <sub>CC</sub> = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	
VI	Input voltage	·	0	5.5	V
V	Output voltage	High or low state	0	$V_{CC}$	V
V <sub>O</sub>		3-state	0	5.5	V
		V <sub>CC</sub> = 1.65 V		-4	
	High lovel output ourrent	V <sub>CC</sub> = 2.3 V		-8	A
I <sub>OH</sub>	High-level output current	$V_{CC} = 2.7 \text{ V}$		-12	mA
		V <sub>CC</sub> = 3 V		-24	
		V <sub>CC</sub> = 1.65 V		4	
	Laur laural autout ausmant	V <sub>CC</sub> = 2.3 V		8	A
l <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2.7 V		12	mA
		V <sub>CC</sub> = 3 V		24	
Δt/Δν	Input transition rise or fall rate			10	ns/V
T <sub>A</sub>	Operating free-air temperature		-40	85	°C

<sup>(1)</sup> All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

<sup>(2)</sup> The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>3)</sup> The value of V<sub>CC</sub> is provided in the recommended operating conditions table.

<sup>(4)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

# SN74LVC823A 9-BIT BUS-INTERFACE FLIP-FLOP WITH 3-STATE OUTPUTS

SCAS305I-MARCH 1993-REVISED FEBRUARY 2005



### **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

P	ARAMETER	TEST C	ONDITIONS	V <sub>cc</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT	
		$I_{OH} = -100 \mu A$		1.65 V to 3.6 V	V <sub>CC</sub> - 0.2				
		$I_{OH} = -4 \text{ mA}$		1.65 V	1.2				
\ <u>\</u>		$I_{OH} = -8 \text{ mA}$		2.3 V	1.7			V	
V <sub>OH</sub>		I <sub>OH</sub> = -12 mA		2.7 V	2.2			V	
		10H = -12 IIIA		3 V	2.4				
		$I_{OH} = -24 \text{ mA}$		3 V	2.2				
	I <sub>OL</sub> = 100 μA			1.65 V to 3.6 V			0.2		
		$I_{OL} = 4 \text{ mA}$		1.65 V			0.45		
$V_{OL}$		I <sub>OL</sub> = 8 mA		2.3 V			0.7	V	
		I <sub>OL</sub> = 12 mA	2.7 V			0.4			
		I <sub>OL</sub> = 24 mA		3 V			0.55		
I		$V_{I} = 0 \text{ to } 5.5 \text{ V}$		3.6 V			±5	μΑ	
I <sub>off</sub>		$V_I$ or $V_O = 5.5 \text{ V}$		0			±10	μΑ	
$I_{OZ}$		$V_0 = 0 \text{ to } 5.5 \text{ V}$		3.6 V			±10	μΑ	
		$V_I = V_{CC}$ or GND	1 - 0	3.6 V			10		
I <sub>CC</sub>	$3.6 \text{ V} \le \text{V}_1 \le 5.5 \text{ V}^{(2)}$		$I_{O} = 0$	3.0 V	10			μΑ	
$\Delta I_{CC}$		One input at V <sub>CC</sub> – 0.6 V,	Other inputs at $V_{CC}$ or GND	2.7 V to 3.6 V			500	μΑ	
C <sub>i</sub>	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND		3.3 V		5		pF	
O <sub>i</sub>	Data inputs	AI = ACC OL GIAD		3.3 V		4		ρι	
Co		$V_O = V_{CC}$ or GND		3.3 V		7		pF	

All typical values are at  $V_{CC}$  = 3.3 V,  $T_{A}$  = 25°C. This applies in the disabled state only.

### **Timing Requirements**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = ± 0.2		V <sub>CC</sub> =	2.7 V	$V_{CC}$ = 3.3 V $\pm$ 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	X
f <sub>clock</sub>	Clock frequency			(1)		(1)		150		150	MHz
t <sub>w</sub> Pulse duration	CLR low	(1)		(1)		3.3		3.3			
	CLK high or low	(1)		(1)		3.3		3.3		ns	
	CLR inactive before CLK↑	(1)		(1)		1		1			
t <sub>su</sub>	Setup time	Data before CLK↑	(1)		(1)		1.3		1.3		ns
	CLKEN low before CLK↑	(1)		(1)		1.8		1.8			
	Hald the e	Data after CLK↑	(1)		(1)		2		2		
τ <sub>h</sub>	t <sub>h</sub> Hold time	CLKEN low after CLK↑	(1)		(1)		1.3		1.3		ns

<sup>(1)</sup> This information was not available at the time of publication.





### **Switching Characteristics**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER FROM (INPUT)		TO (OUTPUT)		$V_{CC}$ = 1.8 V $\pm$ 0.15 V		$V_{CC}$ = 2.5 V $\pm$ 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V	
	(INFOT)	(001F01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			(1)		(1)		150		150		MHz
	CLK	Q	(1)	(1)	(1)	(1)		8.9	1.4	8	20
t <sub>pd</sub>	CLR	Q	(1)	(1)	(1)	(1)		8.8	2.5	7.9	ns
t <sub>en</sub>	ŌĒ	Q	(1)	(1)	(1)	(1)		8.3	1.6	7.2	ns
t <sub>dis</sub>	ŌĒ	Q	(1)	(1)	(1)	(1)		7.1	1.1	6	ns
t <sub>sk(o)</sub>										1	ns

<sup>(1)</sup> This information was not available at the time of publication.

## **Operating Characteristics**

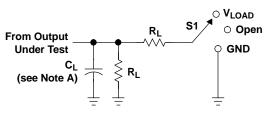
 $T_A = 25^{\circ}C$ 

	PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V TYP	V <sub>CC</sub> = 2.5 V TYP	V <sub>CC</sub> = 3.3 V TYP	UNIT
C	Power dissipation capacitance	Outputs enabled	f = 10 MHz	(1)	(1)	59	pF
Opd	per flip-flop	Outputs disabled	T = TO MINZ	(1)	(1)	46	рг

<sup>(1)</sup> This information was not available at the time of publication.



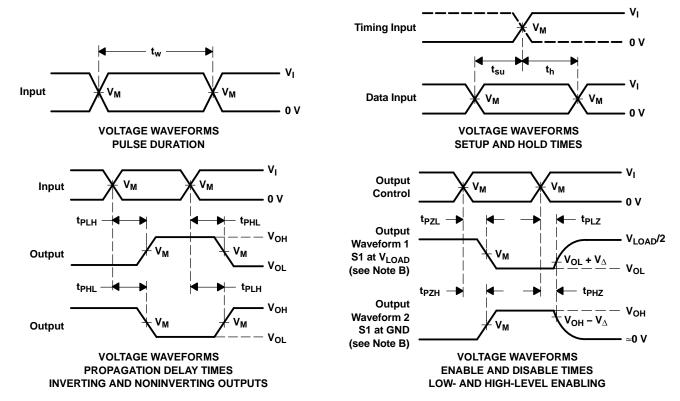
#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

**LOAD CIRCUIT** 

	INF	PUTS	.,	.,		_	.,
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	R <sub>L</sub>	$oldsymbol{V}_{\Delta}$
1.8 V ± 0.15 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

www.ti.com

11-Nov-2025

### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking
	(.,	(=)			(8)	(4)	(5)		(0)
SN74LVC823ADBR	Active	Production	SSOP (DB)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC823A
SN74LVC823ADBR.B	Active	Production	SSOP (DB)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC823A
SN74LVC823ADGVR	Active	Production	TVSOP (DGV)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC823A
SN74LVC823ADGVR.B	Active	Production	TVSOP (DGV)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC823A
SN74LVC823ADW	Active	Production	SOIC (DW)   24	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC823A
SN74LVC823ADW.B	Active	Production	SOIC (DW)   24	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVC823A
SN74LVC823APW	Active	Production	TSSOP (PW)   24	60   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC823A
SN74LVC823APW.B	Active	Production	TSSOP (PW)   24	60   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC823A
SN74LVC823APWR	Active	Production	TSSOP (PW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC823A
SN74LVC823APWR.B	Active	Production	TSSOP (PW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC823A
SN74LVC823APWRG4	Active	Production	TSSOP (PW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC823A
SN74LVC823APWRG4.B	Active	Production	TSSOP (PW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC823A
SN74LVC823APWT	Active	Production	TSSOP (PW)   24	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC823A
SN74LVC823APWT.B	Active	Production	TSSOP (PW)   24	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LC823A

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



## **PACKAGE OPTION ADDENDUM**

www.ti.com 11-Nov-2025

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 9-Oct-2025

### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC823ADBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74LVC823ADGVR	TVSOP	DGV	24	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC823APWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
SN74LVC823APWRG4	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
SN74LVC823APWT	TSSOP	PW	24	250	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1



www.ti.com 9-Oct-2025



#### \*All dimensions are nominal

7 til dillionsions are nominal							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC823ADBR	SSOP	DB	24	2000	353.0	353.0	32.0
SN74LVC823ADGVR	TVSOP	DGV	24	2000	353.0	353.0	32.0
SN74LVC823APWR	TSSOP	PW	24	2000	353.0	353.0	32.0
SN74LVC823APWRG4	TSSOP	PW	24	2000	353.0	353.0	32.0
SN74LVC823APWT	TSSOP	PW	24	250	353.0	353.0	32.0

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 9-Oct-2025

### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74LVC823ADW	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74LVC823ADW.B	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74LVC823APW	PW	TSSOP	24	60	530	10.2	3600	3.5
SN74LVC823APW.B	PW	TSSOP	24	60	530	10.2	3600	3.5





### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



DW (R-PDSO-G24)

# PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.







### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.





NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.





NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



### DB (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE

### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale, TI's General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025